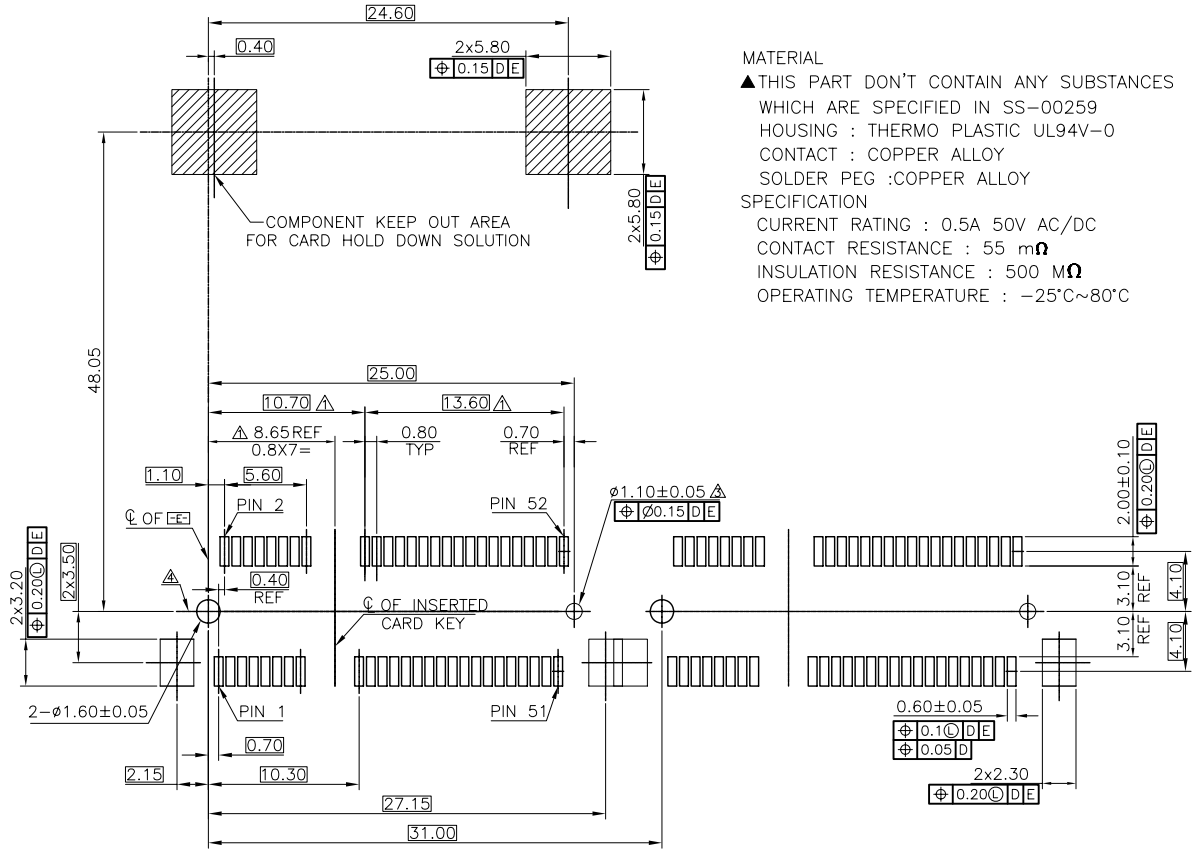
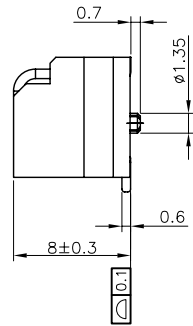
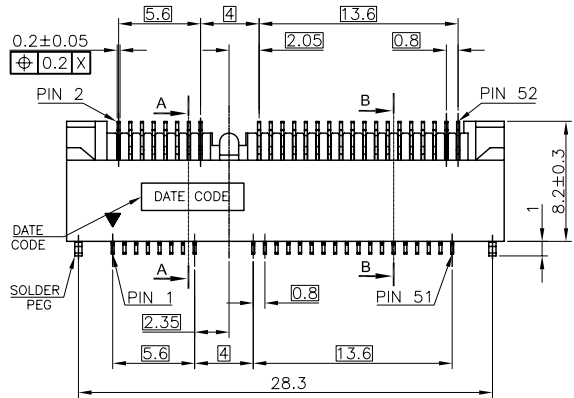
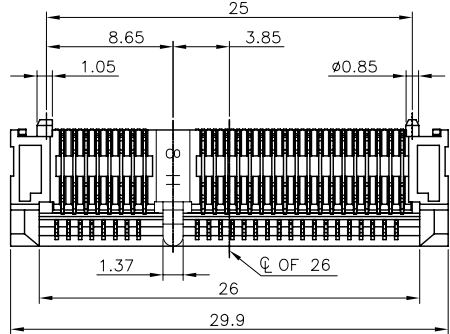


REV.	DESCRIPTION	DATE	DWN	APVD
1	PRELIMINARY	27APR09	JC	BC

Plating : GOLD FLASH 1μ" OVER Ni 50 μ"

MATERIAL
 ▲THIS PART DON'T CONTAIN ANY SUBSTANCES WHICH ARE SPECIFIED IN SS-00259
 HOUSING : THERMO PLASTIC UL94V-0
 CONTACT : COPPER ALLOY
 SOLDER PEG :COPPER ALLOY

SPECIFICATION
 CURRENT RATING : 0.5A 50V AC/DC
 CONTACT RESISTANCE : 55 mΩ
 INSULATION RESISTANCE : 500 MΩ
 OPERATING TEMPERATURE : -25°C~80°C



RECOMMENDED P.C.BOARD PATTERN LAYOUT (SIDE BY SIDE)

GOLD FLASH	J27-0006-01
MIN. GOLD THICKNESS	PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWN 27APR2009
0 PLC ± -	CHK JOHN_CHANG
1 PLC ± 0.3	APVD MARKS_CHEN
2 PLC ± 0.2	APVD BEST_CHANG
3 PLC ± -	PRODUCT SPEC
4 PLC ± -	APPLICATION SPEC
ANGLES ± 3°	WEIGHT - GRAMS
MATERIAL SEE NOTE	DIMENSIONS: MM
FINISH SEE NOTE	
PROJECTION	

HAOGUO XING YE SHARE CO.,LTD.			
0.80MM PITCH MINI PCI EXPRESS H=8.0mm CONNECTOR CUSTOMER DRAWING			
SIZE	DRAWING NO	RESTRICTED TO	
A3	J27-0006	-	
CUSTOMER DRAWING	SCALE -	SHEET 1 OF 1	REV 1

8 7 6 5 4 3 2 1